



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DRA5115G0L

Silicon PNP epitaxial planar type

For digital circuits

Complementary to DRC5115G

DRA2115G in SMini3 type package

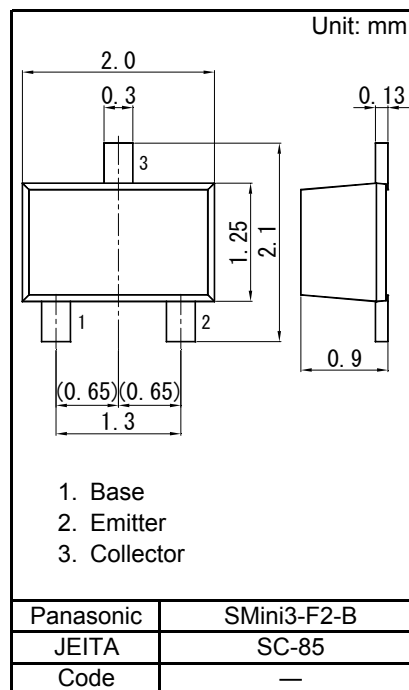
■ Features

- Low collector-emitter saturation voltage $V_{ce(sat)}$
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: LX

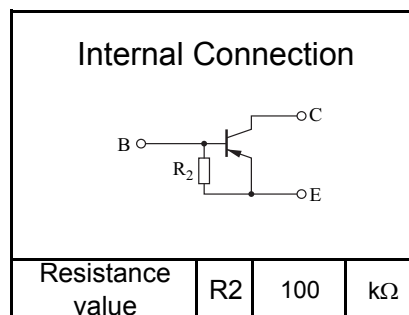
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|--------|-------------|------|
| Collector-base voltage (Emitter open) | VCBO | -50 | V |
| Collector-emitter voltage (Base open) | VCEO | -50 | V |
| Collector current | IC | -100 | mA |
| Total power dissipation | PT | 150 | mW |
| Junction temperature | Tj | 150 | °C |
| Operating ambient temperature | Topr | -40 to +85 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

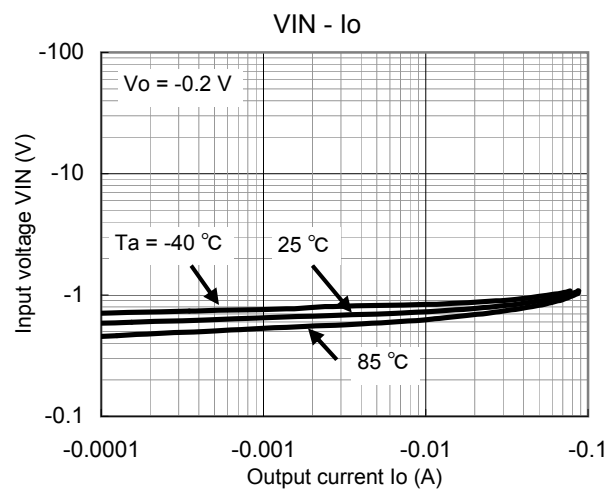
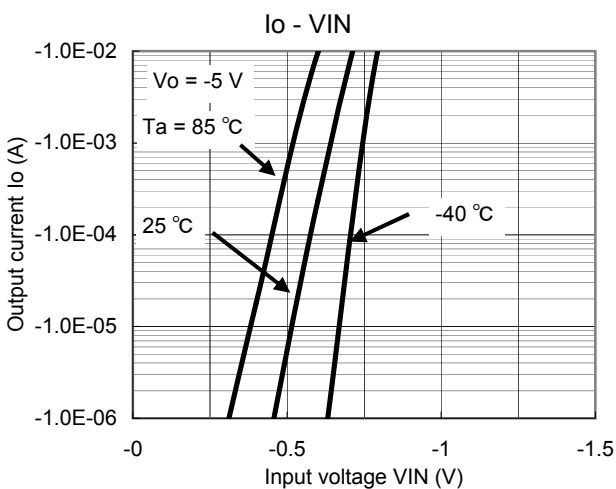
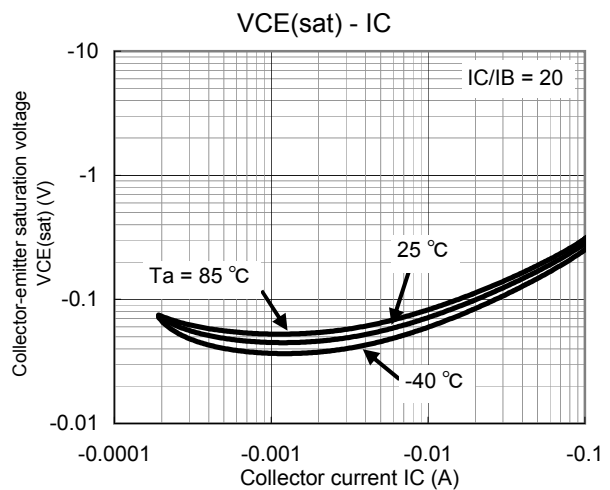
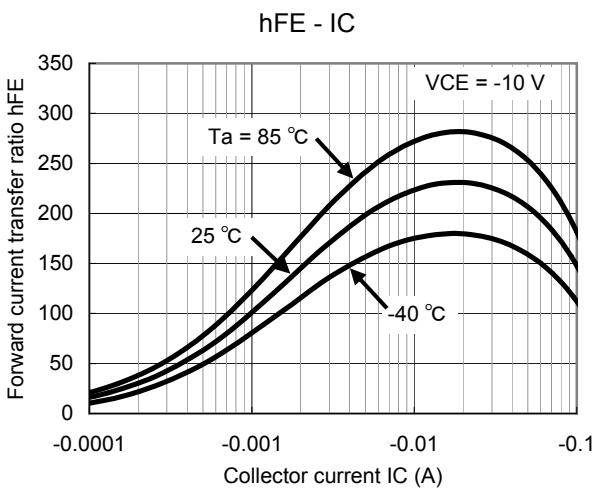
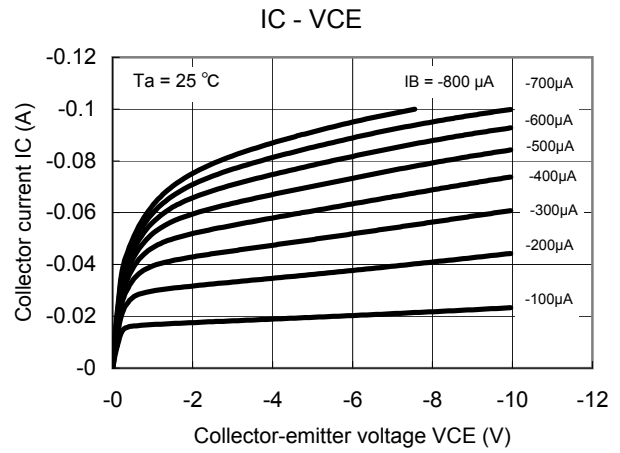
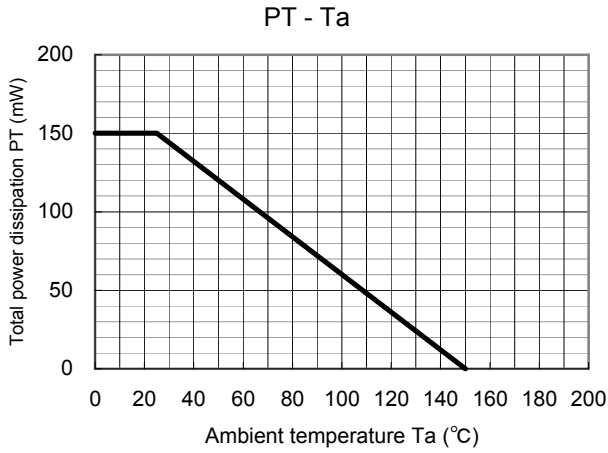


■ Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|----------|---------------------------|------|-----|-------|------|
| Collector-base voltage (Emitter open) | VCBO | IC = -10 μA, IE = 0 | -50 | | | V |
| Collector-emitter voltage (Base open) | VCEO | IC = -2 mA, IB = 0 | -50 | | | V |
| Collector-base cutoff current (Emitter open) | ICBO | VCB = -50 V, IE = 0 | | | -0.1 | μA |
| Collector-emitter cutoff current (Base open) | ICEO | VCE = -50 V, IB = 0 | | | -0.5 | μA |
| Emitter-base cutoff current (Collector open) | IEBO | VEB = -6 V, IC = 0 | | | -0.1 | mA |
| Forward current transfer ratio | hFE | VCE = -10 V, IC = -5 mA | 80 | | | - |
| Collector-emitter saturation voltage | VCE(sat) | IC = -10 mA, IB = -0.5 mA | | | -0.25 | V |
| Input voltage | Vi(on) | VCE = -0.2 V, IC = -5 mA | -0.9 | | | V |
| | Vi(off) | VCE = -5 V, IC = -100 μA | | | -0.4 | V |
| Between emitter base resistance | R2 | | -30% | 100 | +30% | kΩ |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

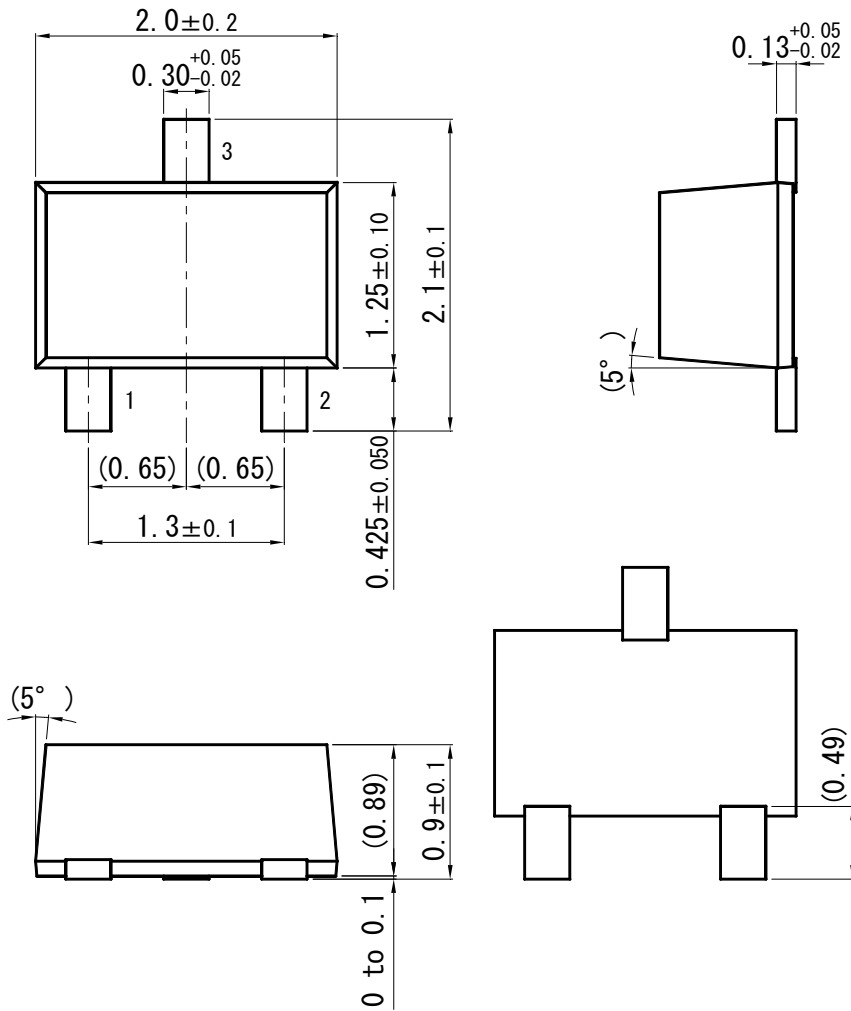
Technical Data (reference)



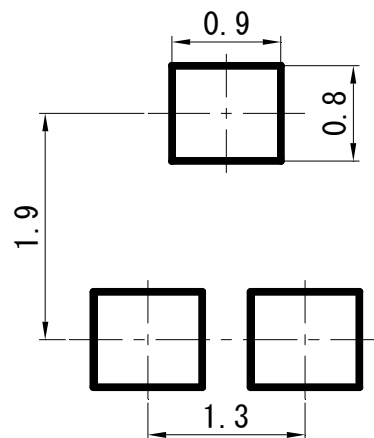


SMini3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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